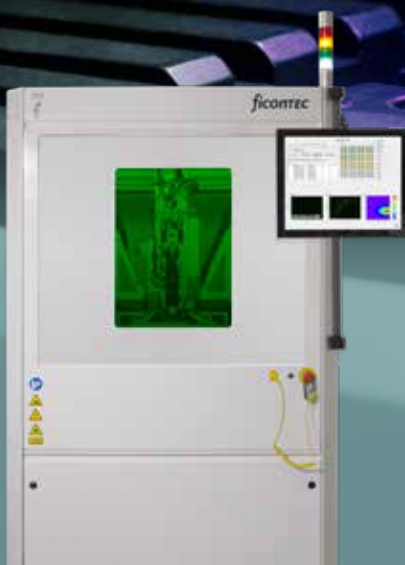




ASSEMBLYLINE

Die-level photonic device assembly

Semi and fully automated development and production systems provide for integration of all optical elements, fibers and fiber arrays, as well as hybridization of die-level PICs and photonic devices. Individually customizable within ficonTEC's high-precision align-&-attach capability suite.



Highlights

- ✓ Reproducible low-loss optical align-&-attach performance
- ✓ Passive/active chip and component placement options
- ✓ A fully customizable and versatile platform 'From Lab to Fab'
- ✓ Applications in PIC hybridization, sensors & lidar, copackaging

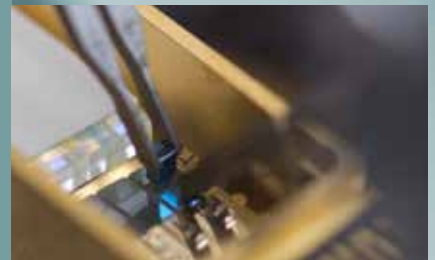


Automated die-level photonic device assembly

ASSEMBLYLINE systems are available as semi and fully automated align-&-attach assembly cells for the development and manufacture of optoelectronics and photonic-enabled devices. They uniquely combine high-precision optical alignment with full bonding capability for all optical elements, waveguides and fiber types as well as for chip and PIC hybridization – all regardless of the material system.

Customizable and versatile from the ground up, ASSEMBLYLINE systems can be configured either as highly capable stand-alone workstations, as highly specific in-line process cells, or used in combination with other functional systems (e.g. TESTLINE) a task-optimized production line configuration to provide volume manufacturing.

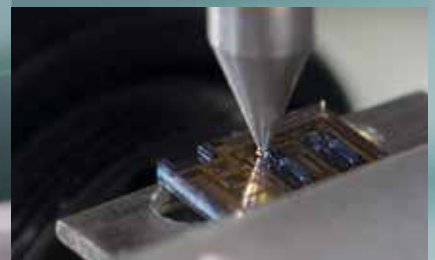
State-of-the-art handling and feed I/O options are available. Optional modules provide features such as automatic tool changing and OCR for component traceability. An add-on AI/ML-based software and hardware layer leverages production data to deliver robust self-adaptive optimization as well as process monitoring and alerting.



Optical element align-&-attach



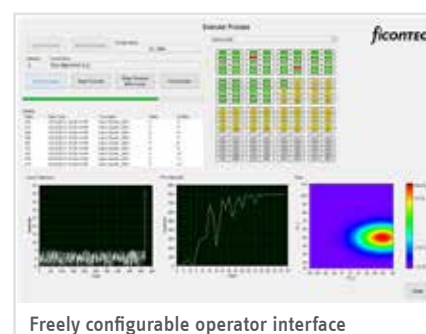
Active fiber (array) alignment



Chip-on-submount bonding

Software control

PCM is ficonTEC's unified process-oriented control interface that ships with all turn-key stand-alone systems and multiple machine configurations. PCM features an intuitive UI and an up-to-date feature set that includes all machine vision, high-resolution positioning, system management software and test routines required to reliably and repeatably drive passive/active alignment and bonding process hardware.

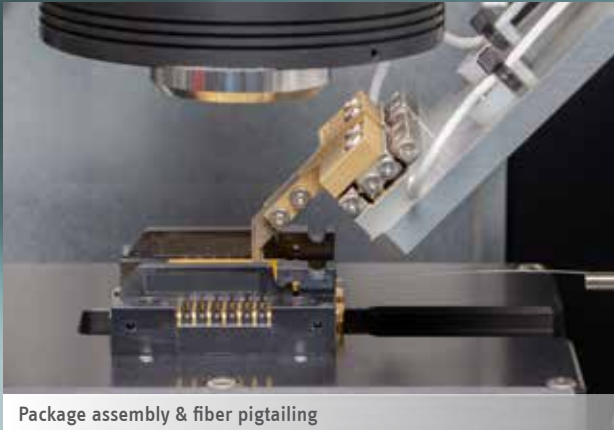


Freely configurable operator interface



ASSEMBLYLINE

Die-level photonic device assembly



Package assembly & fiber pigtailling



Camera module assembly

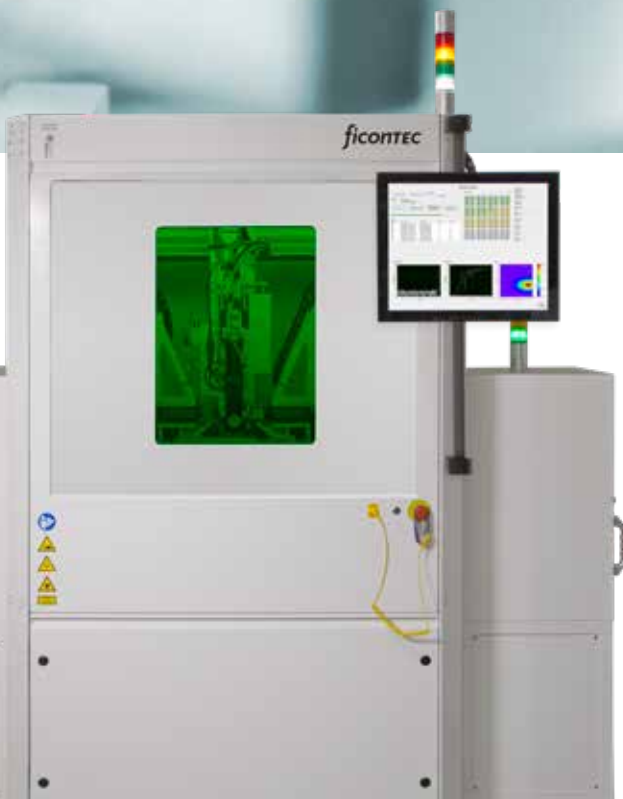


Key features

- High-precision motion referencing and alignment
- Pick-&-place from/to standard/custom carrier formats
- Automated passive and fast-active align-&-attach
- Epoxy and eutectic bonding, laser-assisted soldering
- Fully customizable, flexibly scalable 'From Lab to Fab'

General tasks & applications

- All optical element alignment and device hybridization tasks
- Fiber & waveguide assembly/pigtailling/connectorization
- Optoelectronic, HPLD, MOEMS and sensor assemblies
- Camera modules, 3D scanning & lidar, PICs & silicon photonics
- Configurable for high-complexity copackaged applications



Modular & (re-)configurable

- State-of-the-art die and carrier handling options
- Optional modules expand operational functionality
- Operate, monitor and sync parallel lines remotely
- Add and/or swap modules to re-configure & re-purpose

MANUFACTURING MADE LIGHT

Solutions for integrated photonics. Built to scale.

ficonTEC is the global market leader for automated assembly and test solutions for modern optoelectronics and integrated photonic devices. In serving development and manufacturing needs for telecom/datacom interconnects, sensors & lidar, camera modules, high-power diode lasers and many other integrated applications for over 20 years, ficonTEC's suite of process capabilities is unmatched.

Additionally, a unique and modular approach to production equipment design means that each solution is the automated and optimized embodiment of a customer-defined process.

Contact us

ficonTEC Service GmbH
Achim, Germany

T +49 4202 51160-0
info@ficontec.com

For ficonTEC subsidiaries in the
US and Far East as well as for
distributors around the globe:



www.ficontec.com/locations

Core system specifications	A800	A1200	A1600	A2000
Motion system	minimum 6-axis high-precision alignment*			
Device handling	pick-&-place from/to Gel-Pak, Waffle Pack, custom		pick-&-place from/to Gel-Pak, Waffle Pack, blue tape, custom	
Temperature control	temperature-controlled chuck, +15 to +80 (+/- 0.1) °C			
Load options	manual loading and/or single conveyor	automated loading with single or dual conveyor		
Feed options	suitable for Jedec or Auer boats, or for customer trays			
Machine vision	system referencing and observation camera options device and I/O port referencing			
Software features	flexible and powerful process programming extended operator-less control Windows 10 PC			
Minimum connections	120 VAC (or country specific) air/vacuum 100 Mbit/s network			
Cleanroom compliance	ISO 6**			
Physical features	rugged steel base production cell			
Dimensions (w x b x h, mm)	800 x 1200 x 1600/2000	1200 x 1200 x 2000	1600 x 1200 x 2000	1800 x 1200 x 2000
Weight (typ., kg)	1300	1800	2300	2500

* alternative multi-axis configurations optional ** others available on request

- All ficonTEC systems are compatible with PXI-based electro-optical instrumentation modules and leveraging of NI's LabVIEW™. Non-LabVIEW and alternative instrumentation environments are also compatible.
- In addition to all driving align-&-attach processes, PCM software also includes AI-based Deep Learning defect recognition capability, optional ML-oriented production data monitoring, and can direct call functions in Python files.
- Special purpose cells, robotic systems as well as some TESTLINE functionality can be flexibly incorporated to suit customer needs.